

1 February 2021

POSITIVE RESULTS FROM SECOND NON-PLATFORM LOT

- **Data from the Second Non-Platform Lot demonstrated that the results from First Non-Platform Lot were repeatable**
- **Insights from the Second Non-Platform Lot were incorporated into process conditions for Second Platform Lot**
- **Production of the Second Platform Lot commenced at imec on 27 January 2021**
- **Results from this Second Platform Lot are expected in Q2 of 2021**

Background

On 24 June 2020, 4DS announced the results of its analysis of the Additional Wafers Lot (being the First Non-Platform Lot of 300mm wafers). The First Non-Platform Lot was fabricated with process condition contributions from Western Digital and imec.

The 24 June 2020 announcement stated “it [4DS] has measured the highest speed and endurance in the Additional Wafers Lot that have ever been recorded by the Company:

- The best recorded speed at near DRAM speed exceeds Storage Class Memory requirements without the need for speed crippling error correction;
- Endurance is two to three times better than previously reported. Actual endurance may be significantly higher but is currently not quantified due to available lab time and test equipment capacity; and
- The Company also measured retention and the results remain confidential to the Company and its partners until such time as the upper limits of retention can be more accurately defined.”

Second Non-Platform Lot

Further to the update provided in the Company’s Quarterly Activity Report dated 20 January 2021, 4DS confirms that it has now completed its testing of the Second Non-Platform Lot. The Company is pleased to report that the data from the Second Non-Platform Lot:

- Confirmed that the Company has been able to repeat the results for each of the key memory characteristics (speed, endurance and retention) that were achieved with the First Non-Platform Lot;
- significantly, 19 of the 21 device wafers were functional, a first for the Company (the two nonfunctional wafers were the result of being manufactured outside the imec process window); and
- provides 4DS with further valuable insights with respect to how changes in key process parameters affect these key memory characteristics; i.e. which changes increase which memory characteristic.

Second Platform Lot

The learnings from the Second Non-Platform Lot have been incorporated into the process split conditions for the Second Platform Lot of 300mm wafers. The Second Platform Lot is using imec's memory platform, and contains dense memory arrays with the control logic necessary to read and write selected bits and bytes.

The production of the Second Platform Lot commenced at imec in Belgium on 27 January 2021, and the Company expects to analyse these wafers in Q2 of 2021.

The results from the analysis of the Second Platform Lot are expected to pave the way for 4DS and its partners to pursue their strategic objective of fabricating wafers with chips that operate as fully functional megabit memories, and which have been produced using state of the art industry fab equipment. If successful, this may bring 4DS closer to its 2021 objectives to achieve a potential corporate transaction.

4DS' Managing Director, Dr Guido Arnout stated that "We are pleased that the success of the Second Non-Platform Lot has meant that we were able to immediately commence fabrication of the Second Platform Lot. We are grateful to our partner, imec, for scheduling a slot in its state of the art fab in such a timely manner, particularly given the high demand for access to fab equipment in the current semiconductor market environment."

Drs. Wilbert van den Hoek, 4DS' Chairman, commented "Industry players want to know that a new memory technology can be produced commercially, using industry standard fab equipment. 4DS is well advanced on this path, and the commencement of the Second Platform Lot is another significant step forward."

Authorised for release by the Board.

ENDS

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About 4DS

4DS Memory Limited (ASX: 4DS), with facilities located in Silicon Valley, is a semiconductor development company of non-volatile memory technology, pioneering Interface Switching ReRAM for next generation gigabyte storage in mobile and cloud. Established in 2007, 4DS owns a patented IP portfolio, comprising 29 USA patents granted and 3 patent applications pending and or being filed, which has been developed in-house to create high-density Storage Class Memory. 4DS has a joint development agreement with Western Digital subsidiary HGST, a global storage leader, which accelerates the evolution of 4DS' technology. 4DS also collaborates with imec, a world-leading research and innovation hub in nanoelectronics and digital technologies. The combination of imec's widely acclaimed leadership in microchip technology and profound software and information and communication technology expertise makes them unique.

For more information, please visit www.4dsmemory.com.

About imec

imec is the world-leading research and innovation hub in nanoelectronics and digital technologies. The combination of our widely acclaimed leadership in microchip technology and profound software and ICT expertise is what makes us unique. By leveraging our world-class infrastructure and local and global ecosystem of partners across a multitude of industries, we create ground breaking innovation in application domains such as healthcare, smart cities and mobility, logistics and manufacturing, energy and education.

As a trusted partner for companies, start-ups and universities we bring together close to 3,500 brilliant minds from over 75 nationalities. Imec is headquartered in Leuven, Belgium and also has distributed R&D groups at a number of Flemish universities, in the Netherlands, Taiwan, USA, China, and offices in India and Japan. In 2016, imec's revenue (P&L) totalled 496 million euro. Further information on imec can be found at www.imec-int.com.

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For more information, please visit www.imec.be.

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